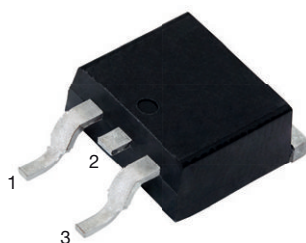
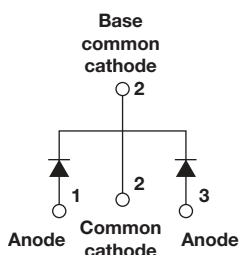


HEXFRED® Ultrafast Soft Recovery Diode, 2 x 4 A


D²PAK (TO-263AB)


FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA08TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 4 A per leg continuous current, the VS-HFA08TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA08TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
V_R	600 V
V_F at I_F	2.2 V
t_{rr} (typ.)	17 ns
T_J max.	150 °C
Package	D²PAK (TO-263AB)
Circuit configuration	Common cathode

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current per leg per device	I_F	$T_C = 100\text{ °C}$	4	A
			8	
			25	
Single pulse forward current	I_{FSM}		16	
Maximum repetitive forward current	I_{FRM}		25	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	25	W
		$T_C = 100\text{ °C}$	10	
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C

**ELECTRICAL SPECIFICATIONS** ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 4.0\text{ A}$	-	1.5	1.8	
		$I_F = 8.0\text{ A}$	-	1.8	2.2	
		$I_F = 4.0\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$	-	1.4	1.7	
Maximum reverse leakage current	I_{RM}	$V_R = V_R\text{ rated}$	-	0.17	3.0	μA
		$T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	44	300	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	4.0	8.0	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6 and 16	t_{rr}	$I_F = 1.0\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	17	-	ns
	t_{rr1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	28	42	
	t_{rr2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	38	57	
Peak recovery current See fig. 7 and 8	I_{RRM1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.9	5.2	A
	I_{RRM2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	3.7	6.7	
Reverse recovery charge See fig. 9 and 10	Q_{rr1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	40	60	nC
	Q_{rr2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	70	105	
Peak rate of fall of recovery current during t_b See fig. 11 and 12	$di_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$	-	280	-	A/ μs
	$di_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$	-	235	-	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	$^{\circ}\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	5.0	K/W
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D ² PAK (TO-263AB)	HFA08TA60CS			

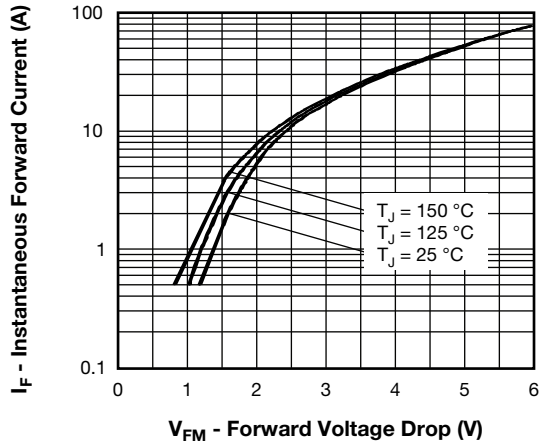


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

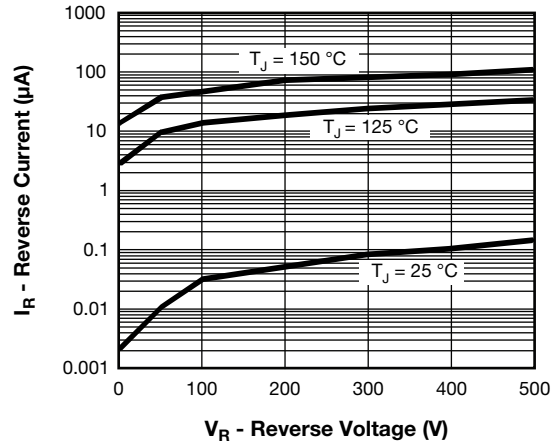


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

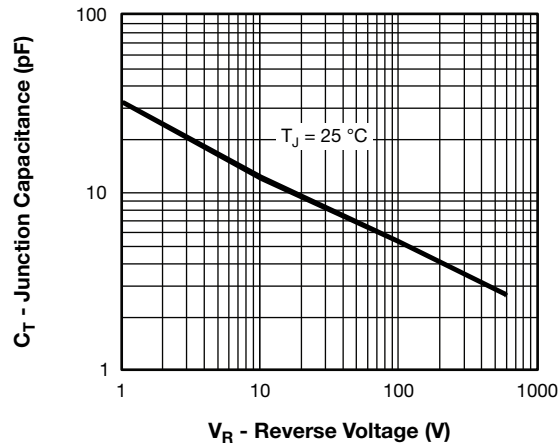


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

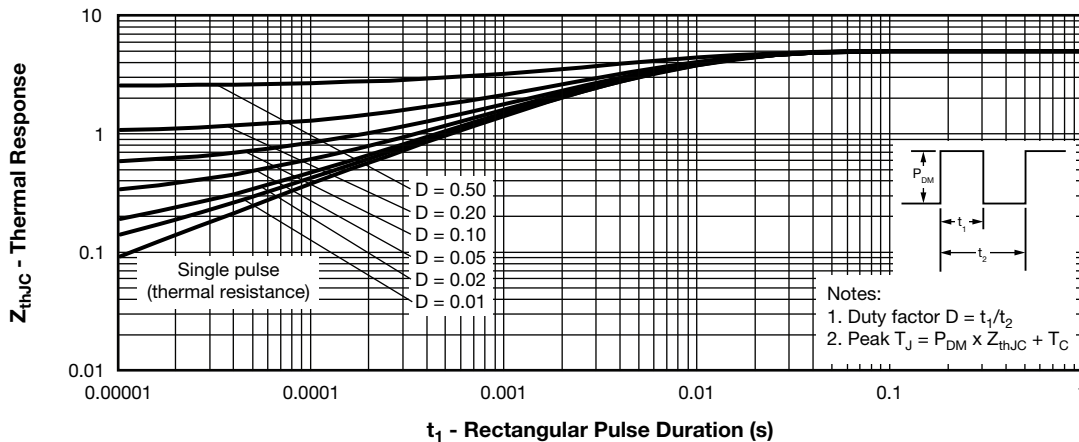
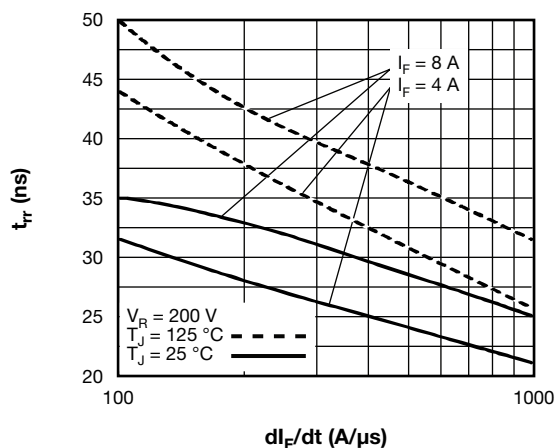
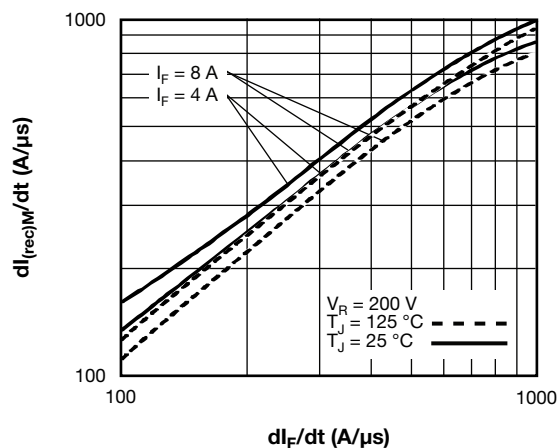
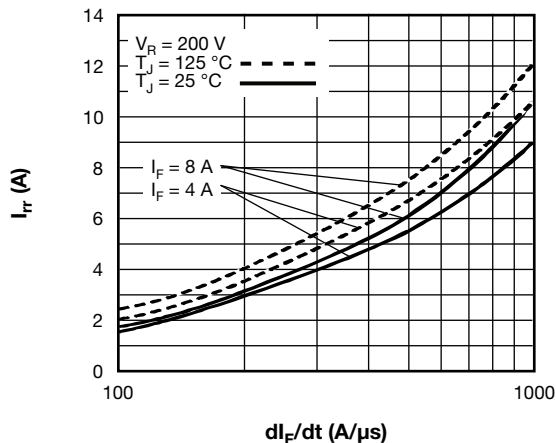
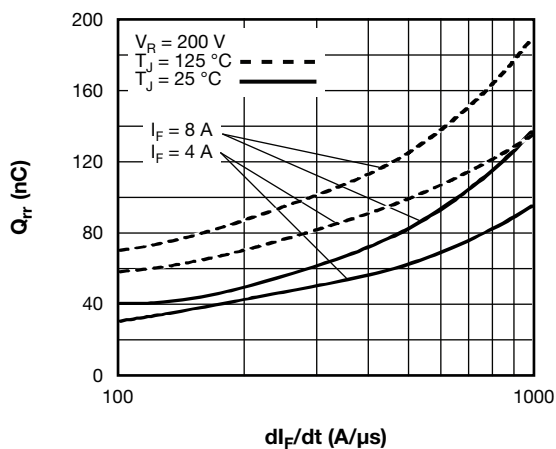


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

Fig. 6 - Typical Recovery Current vs. dI_F/dt

Fig. 7 - Typical Stored Charge vs. dI_F/dt

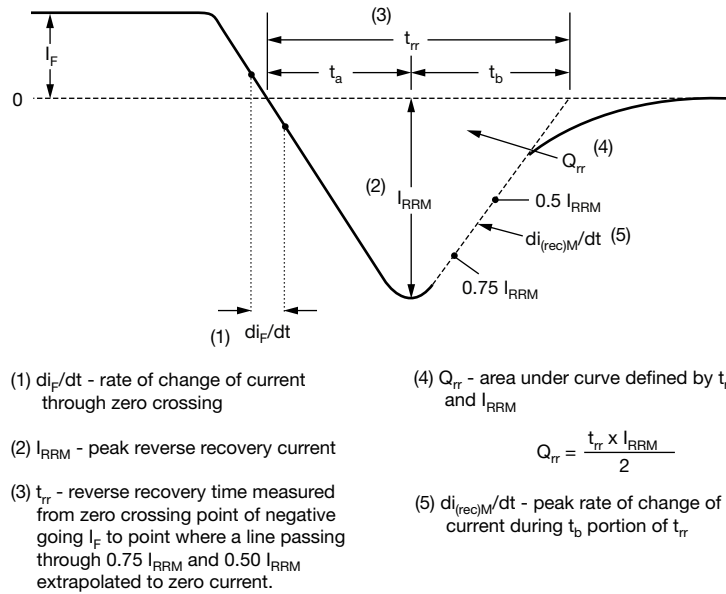


Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code	VS-	HF	A	08	TA	60	C	S	L	-M3
	1	2	3	4	5	6	7	8	9	10

- | | | |
|-----------|---|--|
| 1 | - | Vishay Semiconductors product |
| 2 | - | HEXFRED® family |
| 3 | - | Process designator: A = electron irradiated |
| 4 | - | Current rating (08 = 8 A) |
| 5 | - | Package outline (TA = TO-220, 3 leads) |
| 6 | - | Voltage rating (60 = 600 V) |
| 7 | - | Circuit configuration (C = common cathode) |
| 8 | - | S = D ² PAK (TO-263AB) |
| 9 | - | <ul style="list-style-type: none">• None = tube (50 pieces)• L = tape and reel (left oriented)• R = tape and reel (right oriented) |
| 10 | - | Environmental digit:
-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free |

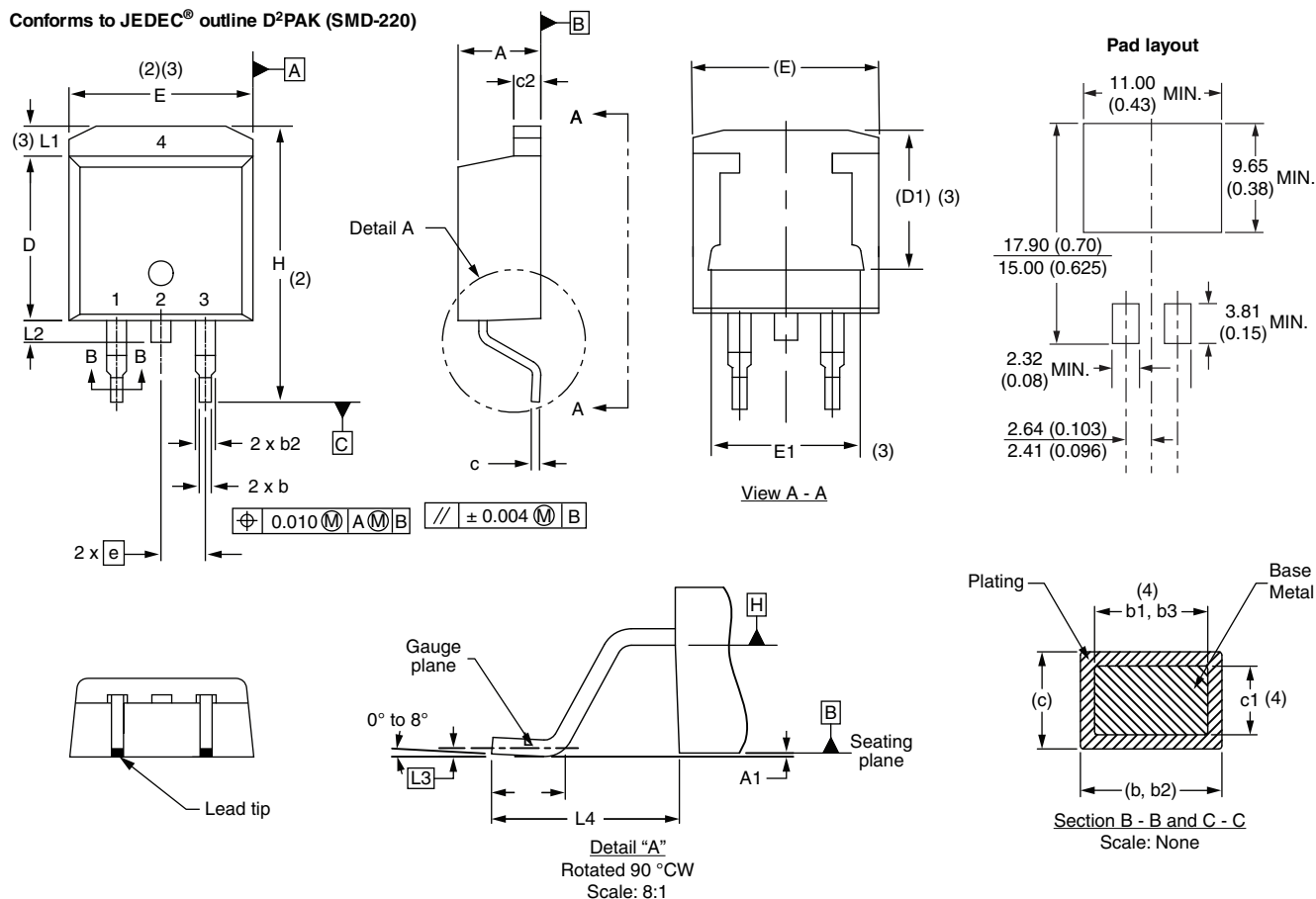
ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-HFA08TA60CS-M3	50	Antistatic plastic tube
VS-HFA08TA60CSR-M3	800	13" diameter reel
VS-HFA08TA60CSL-M3	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96164
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?96424

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB



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